

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPB120N06S4-03	**Issued**	12. December 2014
MA#	MA001055202		
Package	PG-TO263-3-2	**Weight***	1561.04 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.442	0.41	0.41	4127	4127
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		195	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	copper	7440-50-8	304.026	19.48	19.51	194759	195013
wire	non noble metal	aluminium	7429-90-5	9.373	0.60	0.60	6004	6004
encapsulation	organic material	carbon black	1333-86-4	10.168	0.65		6514	
	plastics	epoxy resin	-	111.853	7.17		71653	
	inorganic material	silicondioxide	60676-86-0	555.877	35.60	43.42	356095	434262
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6186	6186
plating	non noble metal	nickel	7440-02-0	0.228	0.01		146	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	356094	146
solder	noble metal	silver	7440-22-4	0.116	0.01		74	
	non noble metal	tin	7440-31-5	0.093	0.01		59	
	non noble metal	lead	7439-92-1	4.430	0.28	0.30	2838	2971
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		351	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	copper	7440-50-8	547.666	35.08	35.13	350835	351291
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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